

RF4E100AJ

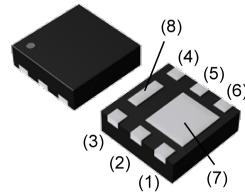
Nch 30V 10A Middle Power MOSFET

| | |
|---------------------|--------|
| V_{DSS} | 30V |
| $R_{DS(on)}$ (Max.) | 12.4mΩ |
| I_D | ±10A |
| P_D | 2.0W |

●Outline

DFN2020-8S

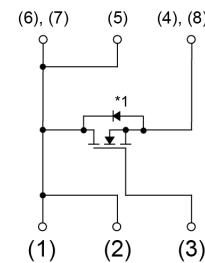
HUML2020L8



●Inner circuit

- (1) Drain
- (2) Drain
- (3) Gate
- (4) Source
- (5) Drain
- (6) Drain
- (7) Drain
- (8) Source

*1 Body Diode



●Packaging specifications

| Type | Packing | Embossed Tape |
|------|---------------------------|---------------|
| | Reel size (mm) | 180 |
| | Tape width (mm) | 8 |
| | Basic ordering unit (pcs) | 3000 |
| | Taping code | TCR |
| | Marking | HV |

●Application

Switching
DC/DC converter
Battery switch

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|---------------|-------------|------|
| Drain - Source voltage | V_{DSS} | 30 | V |
| Continuous drain current | I_D | ±10 | A |
| Pulsed drain current | I_{DP}^{*1} | ±36 | A |
| Gate - Source voltage | V_{GSS} | ±12 | V |
| Avalanche current, single pulse | I_{AS}^{*2} | 2.7 | A |
| Avalanche energy, single pulse | E_{AS}^{*2} | 6.7 | mJ |
| Power dissipation | P_D^{*3} | 2.0 | W |
| Junction temperature | T_j | 150 | °C |
| Operating junction and storage temperature range | T_{stg} | -55 to +150 | °C |

● Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|--|-----------------|--------|------|------|------|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - ambient | R_{thJA}^{*3} | - | - | 62.5 | °C/W |

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|--|---|---|--------|------|-----------|-------|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{V}, I_D = 1\text{mA}$ | 30 | - | - | V |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$ | $I_D = 1\text{mA}$ referenced to 25°C | - | 18 | - | mV/°C |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$ | - | - | 1 | μA |
| Gate - Source leakage current | I_{GSS} | $V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$ | - | - | ± 100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 1\text{mA}$ | 0.5 | - | 1.5 | V |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | $I_D = 1\text{mA}$ referenced to 25°C | - | -1.8 | - | mV/°C |
| Static drain - source on - state resistance | $R_{DS(on)}^{*4}$ | $V_{GS} = 4.5\text{V}, I_D = 10\text{A}$ $V_{GS} = 2.5\text{V}, I_D = 5.0\text{A}$ | - | 9.4 | 12.4 | mΩ |
| Gate resistance | R_G | f=1MHz, open drain | - | 1.1 | - | |
| Forward Transfer Admittance | $ Y_{fs} ^{*4}$ | $V_{DS} = 5\text{V}, I_D = 3\text{A}$ | 6.0 | - | - | S |

*1 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*2 $L \approx 1\text{mH}, V_{DD} = 15\text{V}, R_G = 25\Omega$, STARTING $T_j = 25^\circ\text{C}$ Fig.3-1,3-2

*3 Mounted on a Cu Board (40×40×0.8mm)

*4 Pulsed

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|------------------------------|-------------------|---|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Input capacitance | C_{iss} | $V_{GS} = 0\text{V}$ $V_{DS} = 15\text{V}$ $f = 1\text{MHz}$ | - | 1460 | - | pF |
| Output capacitance | C_{oss} | | - | 170 | - | |
| Reverse transfer capacitance | C_{rss} | | - | 115 | - | |
| Turn - on delay time | $t_{d(on)}^{*4}$ | $V_{DD} \approx 15\text{V}, V_{GS} = 4.5\text{V}$ $I_D = 5\text{A}$ $R_L \approx 3\Omega$ $R_G = 10\Omega$ | - | 21 | - | ns |
| Rise time | t_r^{*4} | | - | 21 | - | |
| Turn - off delay time | $t_{d(off)}^{*4}$ | | - | 54 | - | |
| Fall time | t_f^{*4} | | - | 20 | - | |

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------|---------------|---|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Total gate charge | Q_g^{*4} | $V_{DD} \approx 15\text{V}$, $I_D = 10\text{A}$, $V_{GS} = 4.5\text{V}$ | - | 13.0 | - | nC |
| Gate - Source charge | Q_{gs}^{*4} | | - | 3.3 | - | |
| Gate - Drain charge | Q_{gd}^{*4} | | - | 3.2 | - | |

● Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------------|---------------|---|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Continuous forward current | I_S | $T_a = 25^\circ\text{C}$ | - | - | 1.67 | A |
| Pulse forward current | I_{SP}^{*1} | | - | - | 36 | A |
| Forward voltage | V_{SD}^{*4} | $V_{GS} = 0\text{V}$, $I_S = 1.67\text{A}$ | - | - | 1.2 | V |

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

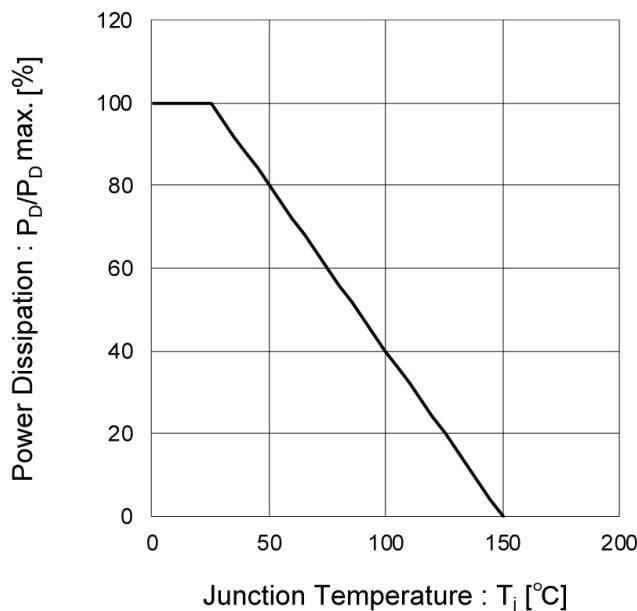


Fig.2 Maximum Safe Operating Area

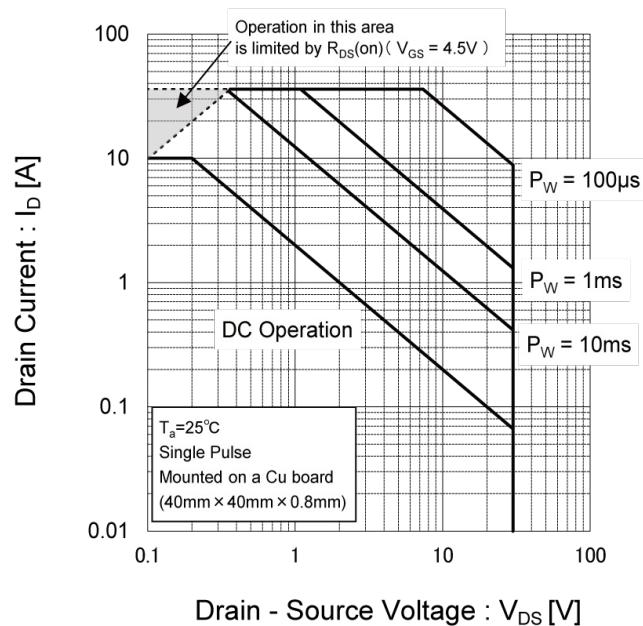


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

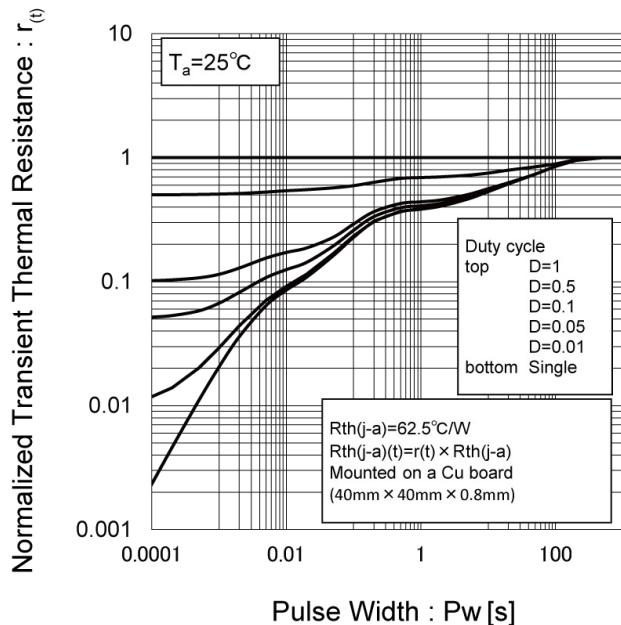
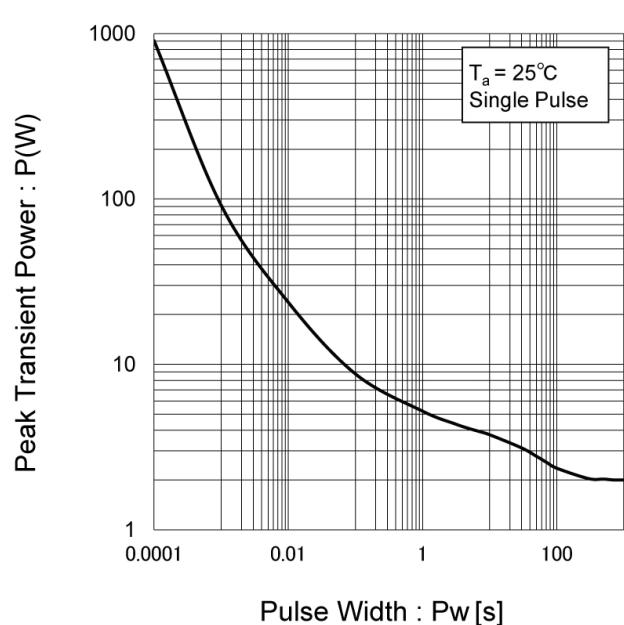


Fig.4 Single Pulse Maximum Power dissipation



● Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

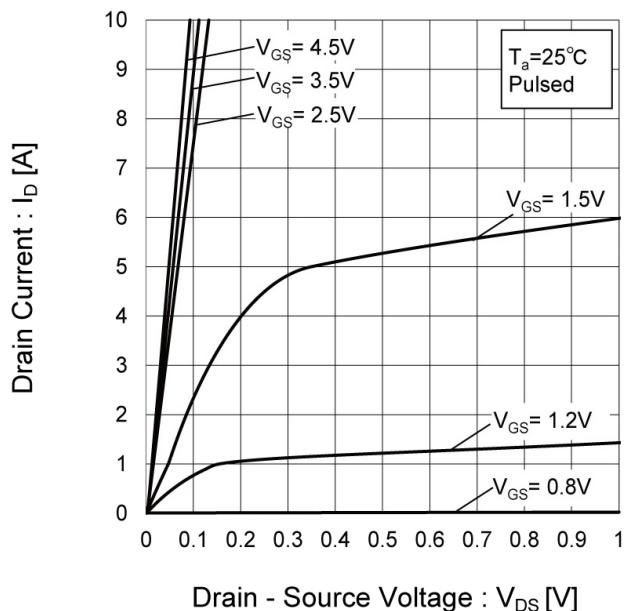


Fig.6 Typical Output Characteristics(II)

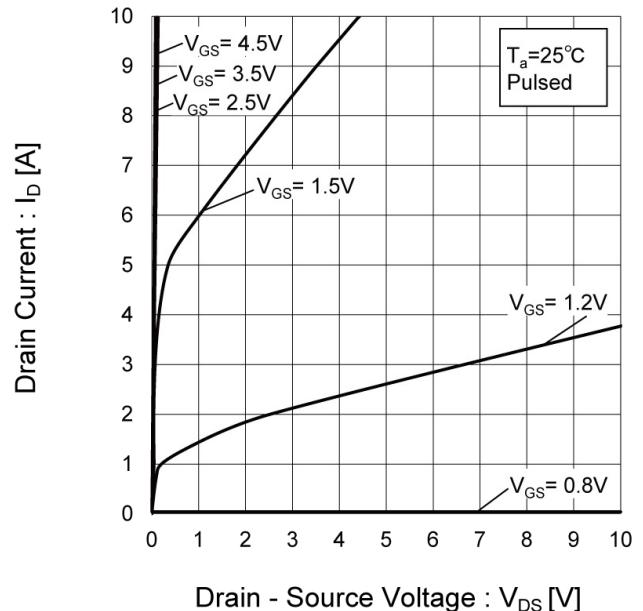
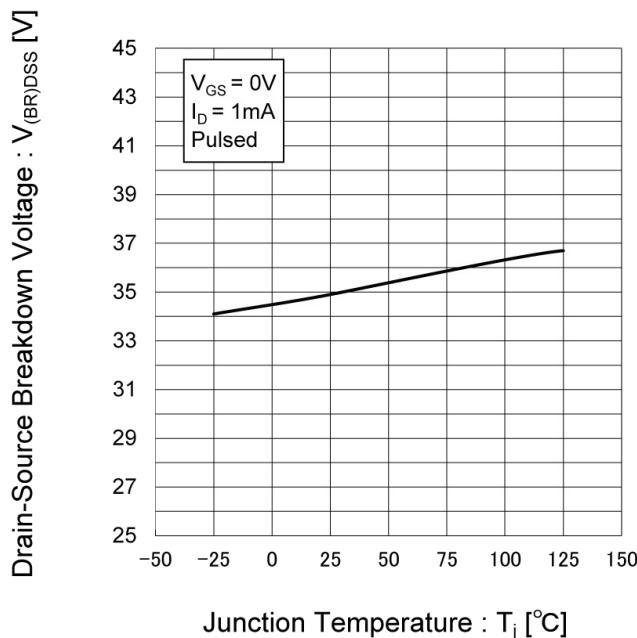


Fig.7 Breakdown Voltage vs.
Junction Temperature



● Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

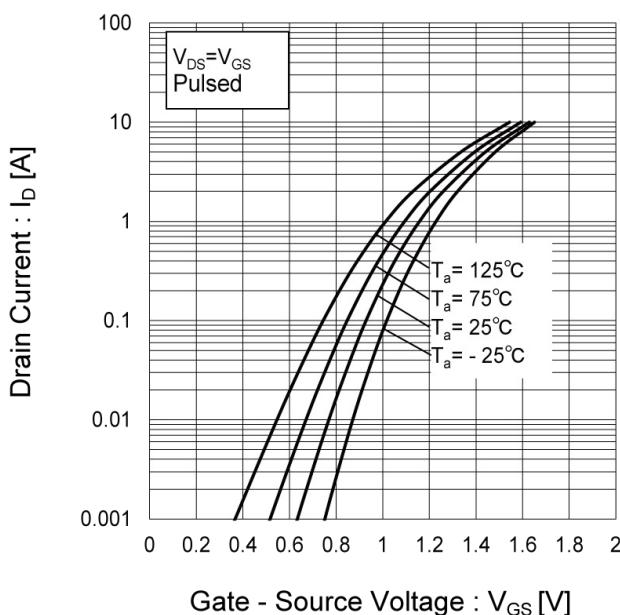


Fig.9 Gate Threshold Voltage vs. Junction Temperature

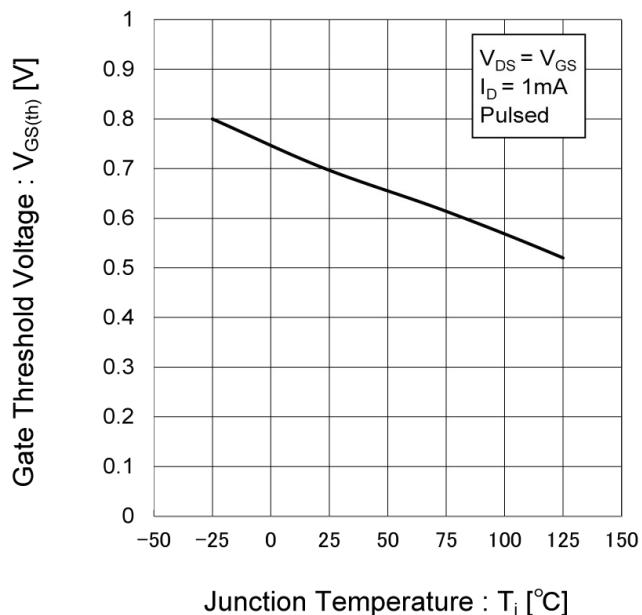
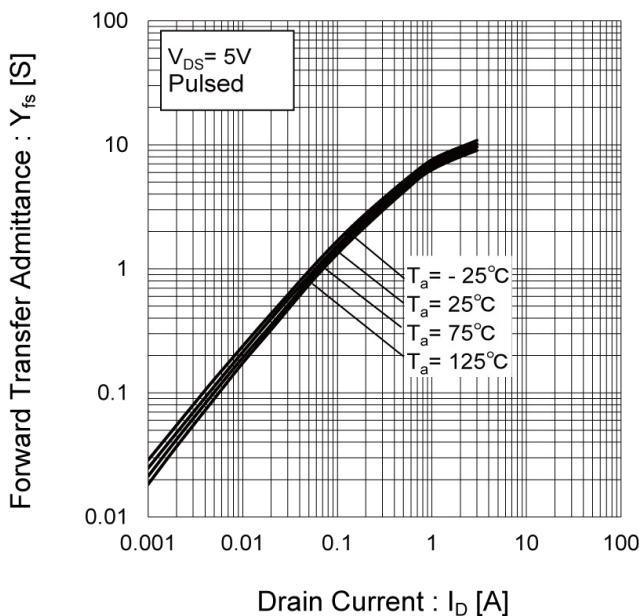


Fig.10 Forward Transfer Admittance vs. Drain Current



● Electrical characteristic curves

Fig.11 Drain Current Derating Curve

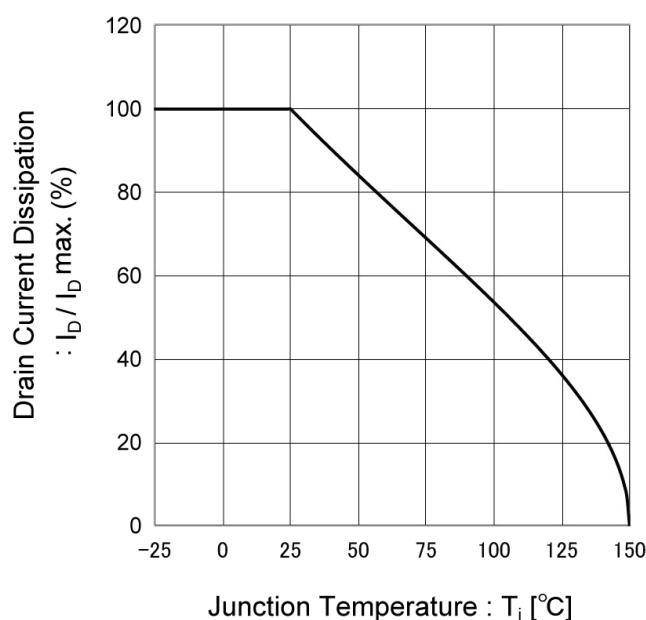


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

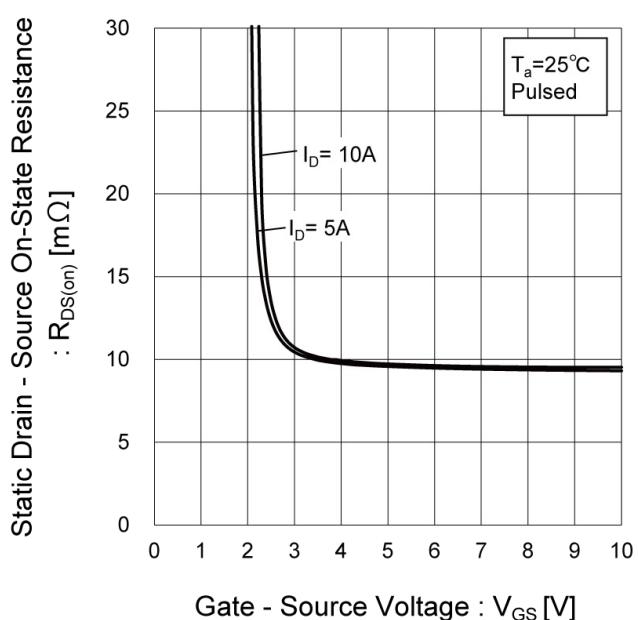
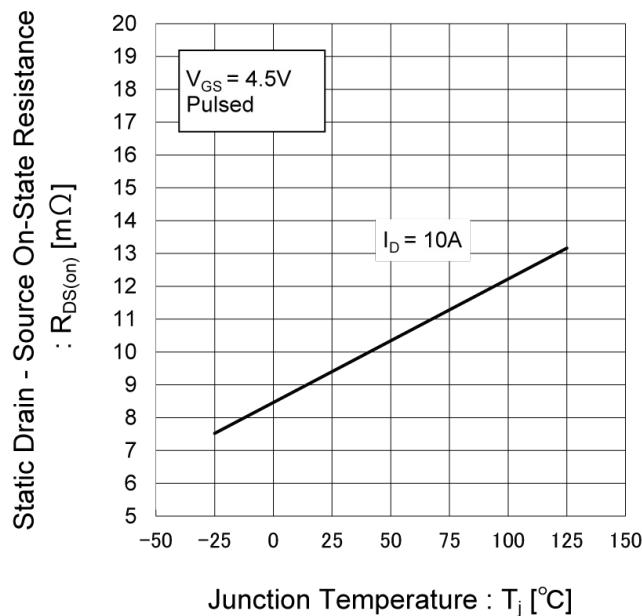


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



● Electrical characteristic curves

Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

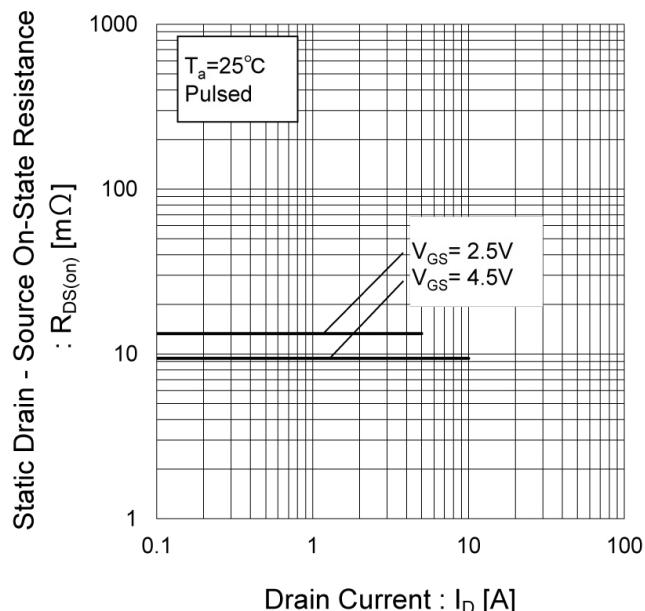


Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current (II)

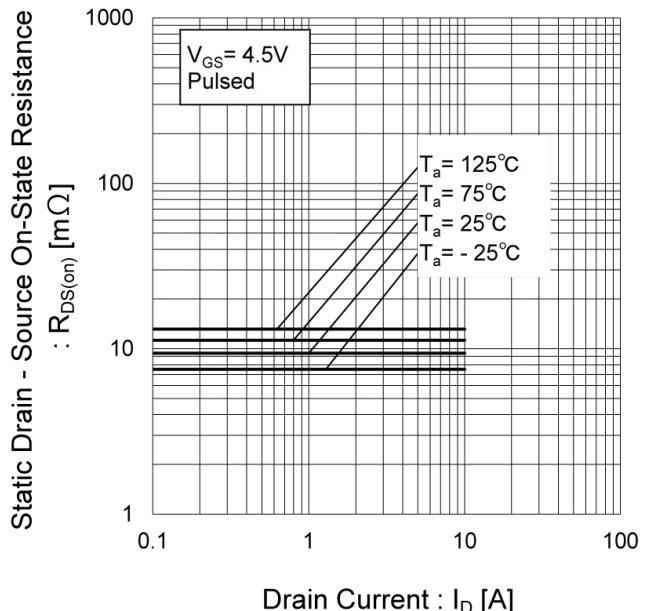
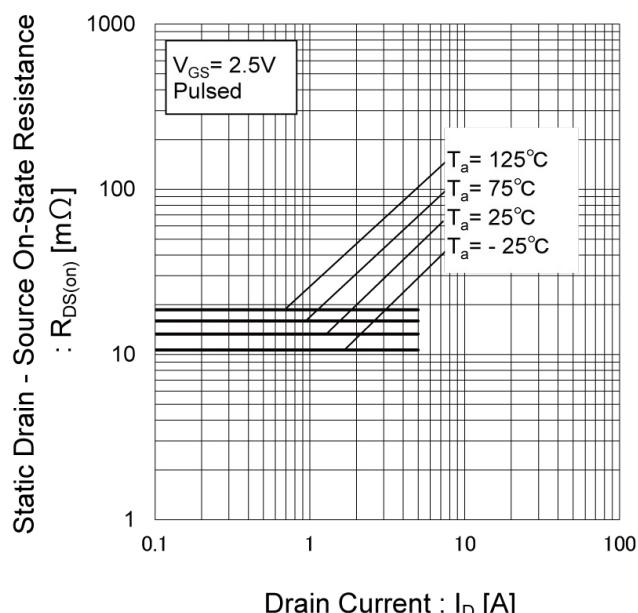


Fig.16 Static Drain - Source On - State
Resistance vs. Drain Current (III)



● Electrical characteristic curves

Fig.17 Typical Capacitance vs.
Drain - Source Voltage

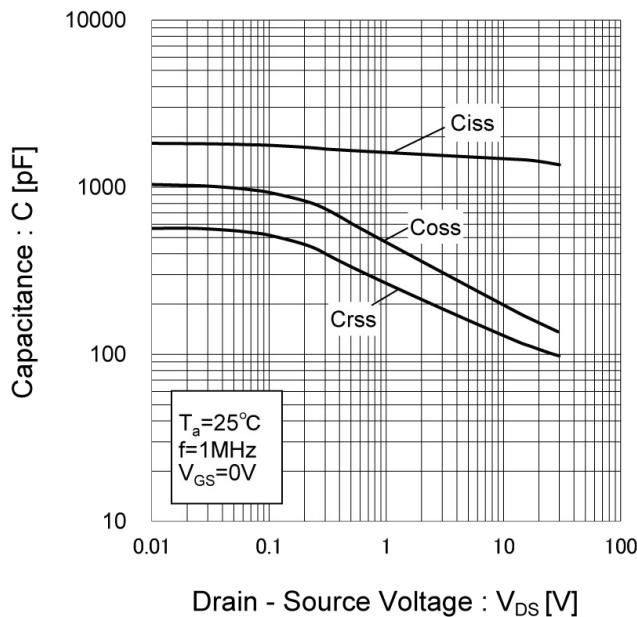


Fig.18 Switching Characteristics

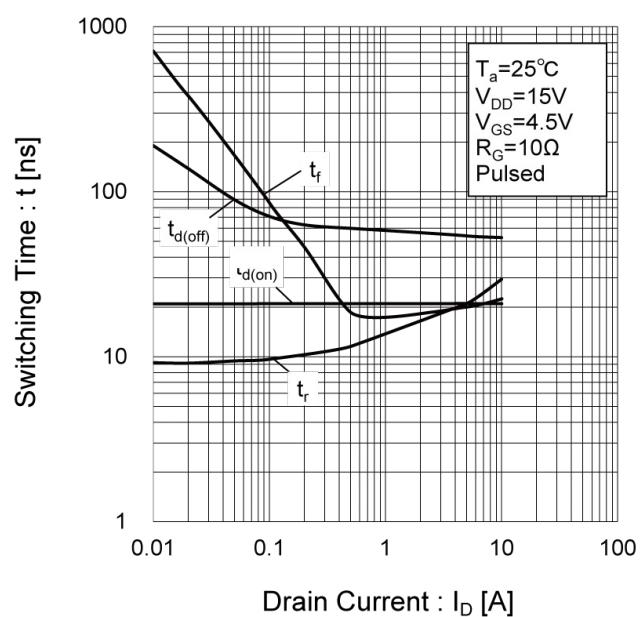


Fig.19 Dynamic Input Characteristics

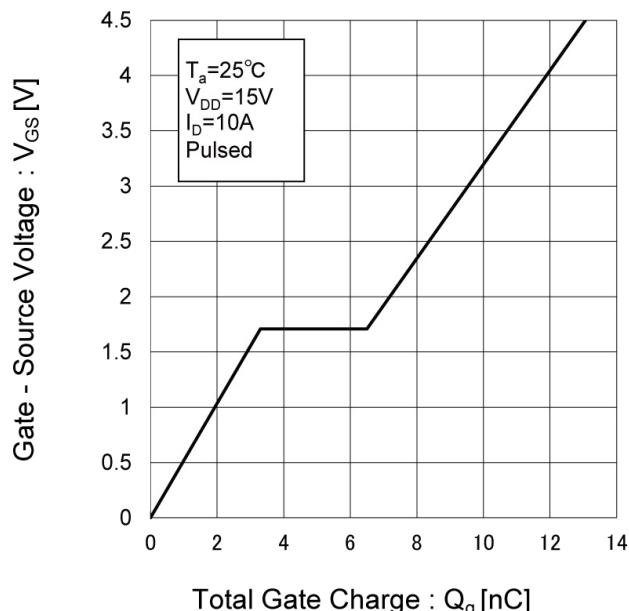
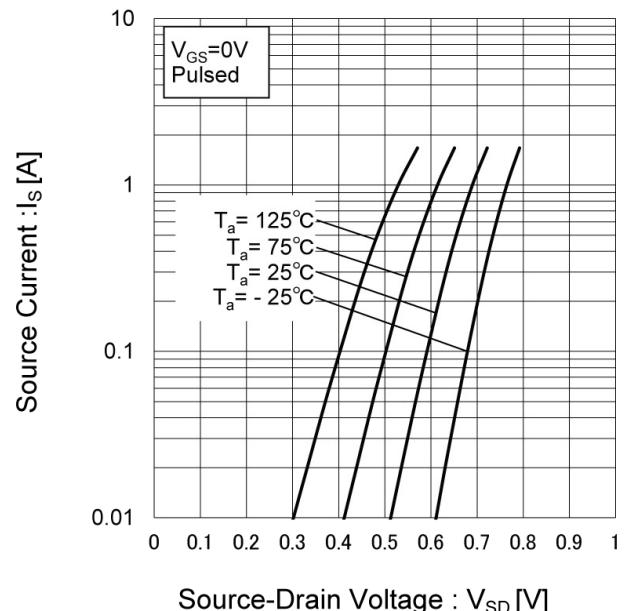


Fig.20 Source Current vs. Source Drain Voltage



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

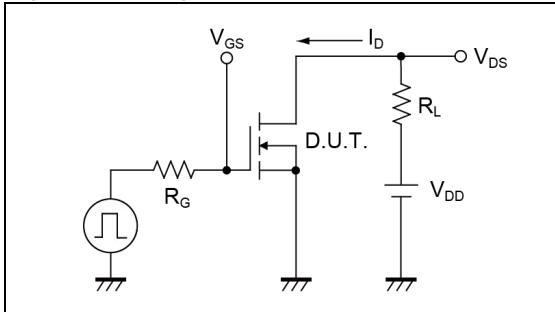


Fig.1-2 Switching Waveforms

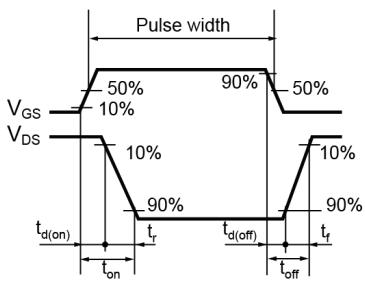


Fig.2-1 Gate Charge Measurement Circuit

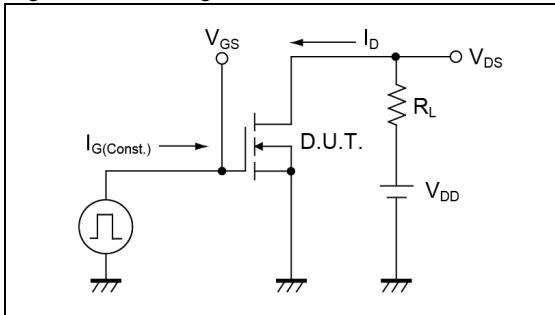


Fig.2-2 Gate Charge Waveform

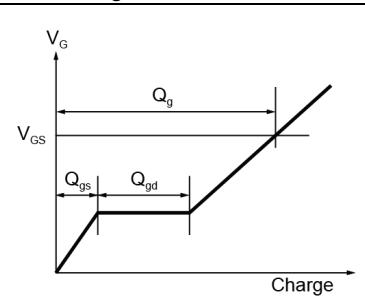


Fig.3-1 Avalanche Measurement Circuit

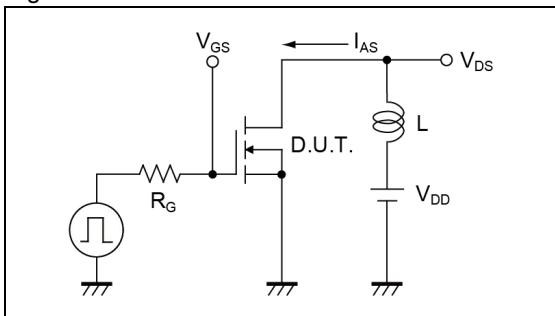
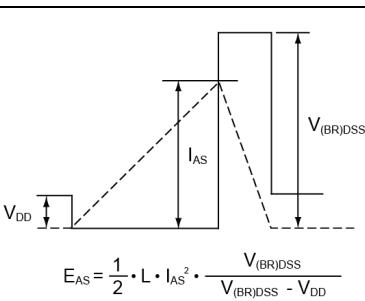


Fig.3-2 Avalanche Waveform



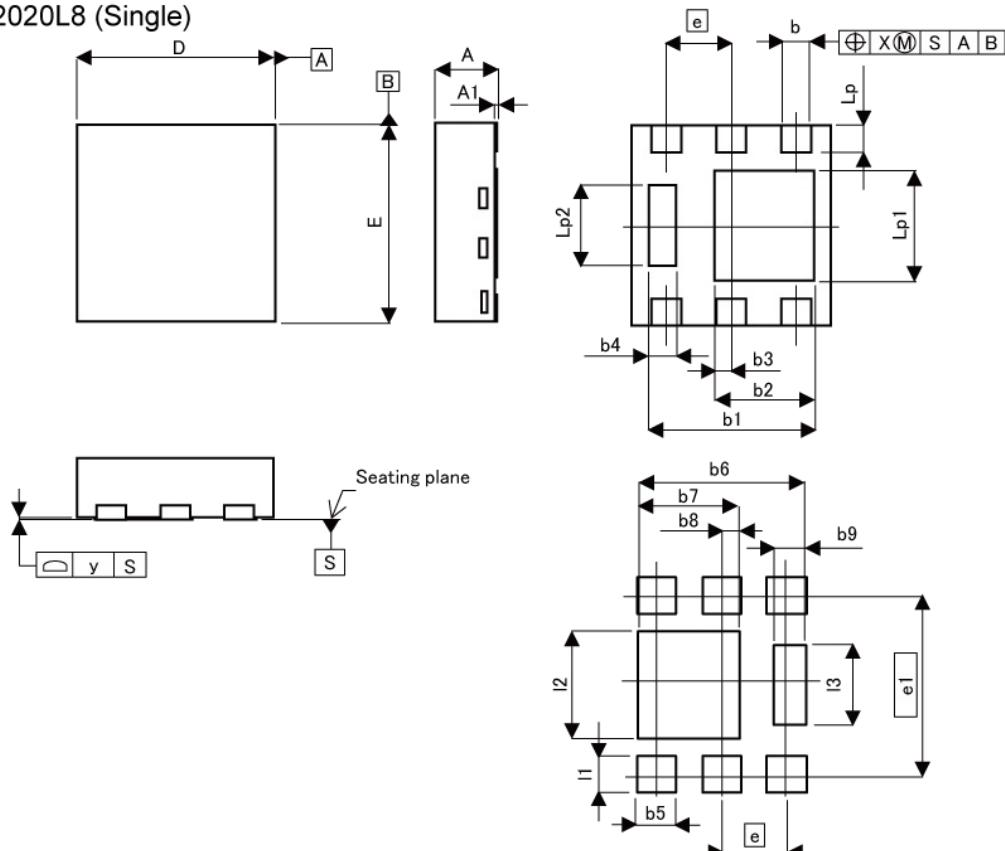
● Notice

This product might cause chip aging and breakdown under the large electrified environment.
Please consider to design ESD protection circuit.

●Dimensions

DFN2020-8S

HUML2020L8 (Single)



Pattern of terminal position areas
[Not a pattern of soldering pads]

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.55 | 0.65 | 0.022 | 0.026 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| b1 | 1.55 | 1.75 | 0.061 | 0.069 |
| b2 | 0.95 | 1.05 | 0.037 | 0.041 |
| b3 | 0.175 | | 0.007 | |
| b4 | 0.20 | 0.30 | 0.008 | 0.012 |
| D | 1.90 | 2.10 | 0.075 | 0.083 |
| E | 1.90 | 2.10 | 0.075 | 0.083 |
| e | 0.65 | | 0.026 | |
| Lp | 0.225 | 0.325 | 0.009 | 0.013 |
| Lp1 | 1.05 | 1.15 | 0.041 | 0.045 |
| Lp2 | 0.75 | 0.85 | 0.030 | 0.033 |
| x | - | 0.10 | - | 0.004 |
| y | - | 0.10 | - | 0.004 |

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| b5 | - | 0.45 | - | 0.018 |
| b6 | - | 1.75 | - | 0.069 |
| b7 | - | 1.05 | - | 0.041 |
| b8 | 0.175 | | 0.007 | |
| b9 | - | 0.30 | - | 0.012 |
| e1 | 1.725 | | 0.068 | |
| l1 | - | 0.425 | - | 0.017 |
| l2 | - | 1.15 | - | 0.045 |
| l3 | - | 0.85 | - | 0.033 |

Dimension in mm/inches